IN THE CLAIMS

Listing of Claims:

| 1 | 1. (currently amended) A method for managing power utilization and performance of a |
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| 2 | multiprocessor (MP) system comprising the steps of: |
| 3 | receiving first sensor data defining physical parameters of said MP system; |
| 4 | receiving first parameters corresponding to customer level operational |
| 5 | requirements of said MP system; |
| 6 | determining power and performance goal settings for processors in said MP |
| 7 | system in response to said first sensor data and said first parameters; |
| 8 | generating a set of controls for said MP system in response to said power and |
| 9 | performance goal settings; and |
| 10 | applying said set of controls to adjust operation parameters of said processors in |
| 11 | said MP system. |
| | |
| 1 | 2. (original) The method of claim 1, wherein said method further comprises the step of: |
| 2 | applying said controls to adjust operation parameters of cooling systems for said |
| 3 | MP system. |
| | |
| 1 | 3. (original) The method of claim 1, wherein said MP system comprises a single |
| 2 | multiprocessor very large scale integrated circuit (VLSI) chip. |
| • | 4 (' ' 1) The control of Calabara 2 and control MD control commission a continu |
| 1 | 4. (original) The method of claim 3, wherein said MP system comprises a cooling |
| 2 | means for said multiprocessor VLSI chip. |
| 1 | 5. (original) The method of claim 4, wherein said cooling means comprises a single chip |
| 2 | cooling fan. |
| | |
| 1 | 6. (original) The method of claim 4, wherein said cooling means comprises a |
| 2 | controllable single chip thermo-electric cooler. |

7. (original) The method of claim 3, wherein said MP system comprises a self-contained

- 2 MP system, said self-contained MP system comprising a plurality of said multiprocessor
- 3 VLSI chips, said self-contained MP system further comprising a first controllable cooling
- 4 system.
- 8. (original) The method of claim 7, wherein said MP system comprises a rack MP
- 2 system, said rack MP system comprising a plurality of said self-contained MP systems
- and a controllable rack cooling system.
- 9. (original) The method of claim 8, wherein said MP system comprises a plurality of
- 2 said rack MP systems, said MP system further comprising a controllable MP system
- 3 cooling means.
- 1 10. (original) The method of claim 1, wherein said first sensor data comprises
- temperatures of said processors in said MP system, supply voltages corresponding to
- 3 circuits in said processors, clock frequencies of said processors, electromagnetic radiation
- 4 (EMC) of said MP system, acoustic levels of said MP system, vibration levels of said MP
- 5 system, and air temperatures of cooling systems in said MP system.
- 1 11. (currently amended) The method of claim 1, wherein said first parameters comprise
- 2 customer level quality of service parameters for said MP system.
- 1 12. (original) The method of claim 1, wherein said first parameters comprise policy of
- 2 operation parameters for said MP system.
- 1 13. (original) The method of claim 11, wherein said quality of service parameters
- 2 comprise assignment data defining processor assignment to tasks performed by said MP
- 3 system, access availability data for processors in said MP system, performance level data
- 4 defining a performance for an application executing on processors of said MP system,
- 5 and processor operational data defining which of said processors are operational.

1 14. (original) The method of claim 12, wherein said policy of operation parameters comprise data defining a cost of power for said MP system, acceptable acoustic noise 2 level data for said MP system, acceptable EMC output noise level data for said MP 3 4 system, acceptable output vibration level data of said MP system and acceptable 5 temperature level data for elements of said MP system. 15. (original) The method of claim 1, wherein said power and performance goals 1 2 comprise data defining a desired MP system power consumption level, data defining a 3 desired processor power consumption level, data defining desired MP system 4 temperatures, desired MP acoustic noise output levels, desired EMC noise levels, and 5 desired processor instruction execution speeds. 1 16. (original) The method of claim 1, wherein said set of controls comprise power 2 supply voltage settings for said processors, clock frequency settings for said processors, 3 cooling fan speeds, controls for said MP system cooling means and operational mode 4 settings for said processors. 1 17. (original) The method of claim 16, wherein said operational mode settings comprise an active mode and a sleep low power mode. 2 1 18. (original) The method of claim 16, wherein said MP system cooling means 2 comprises channeled temperature conditioned air. 1 19. (currently amended) A controller for managing power and performance in a multiprocessor MP system comprising: 2 3 a first receiving circuit operable to receive first sensor data corresponding to physical parameters of said MP system; 4 a second receiving circuit operable to receive first parameters defining customer 5

level quality of service operational requirements of said MP system;

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| , | a tillid circuit operable to determine power and performance goal settings for said |
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| 8 | processors in said MP system in response to said first data and said first parameters; |
| 9 | a fourth circuit operable to generate a set of controls for said MP system in |
| 10 | response to said power and performance goal settings; and |
| 11 | a fifth circuit operable to apply said set of controls to adjust operation parameters |
| 12 | of said processors in said MP system. |
| 1 | 20. (original) The controller of claim 19, wherein said fifth circuit is further operable to |
| 2 | apply said set of controls to adjust operation parameters of cooling systems of said MP |
| 3 | system. |
| | |
| 1 | 21. (original) The controller of claim 19, wherein said set of controls comprise power |
| 2 | supply voltage settings for said processors, clock frequency settings for said processors, |
| 3 | cooling fan speeds, controls for said MP system cooling means and operational mode |
| 4 | settings for said processors. |
| 1 | 22. (original) The controller of claim 21, wherein said operational mode settings |
| 2 | comprise an active mode and a sleep low power mode. |
| | |
| 1 | 23. (original) The controller of claim 21, wherein said MP system cooling means |
| 2 | comprises channeled temperature conditioned air, chilled fluid and solid state cooling |
| 3 | units. |
| 1 | 24. (currently amended) A multiprocessor (MP) system comprising a plurality of |
| 2 | processors and a controller for managing power and performance in said MP system, said |
| 3 | controller further comprising: |
| | circuitry for receiving first sensor data defining physical parameters of said MP |
| 4 | |
| 5 | system; |

| 6 | circuitry for receiving first parameters corresponding to customer level quality of |
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| 7 | service operational requirements of said MP system; |
| 8 | circuitry for determining power and performance goal settings for processors in |
| 9 | said MP system in response to said first sensor data and said first parameters; |
| 10 | circuitry for generating a set of controls for said MP system in response to said |
| 11 | power and performance goal settings; and |
| 12 | circuitry for applying said set of controls to adjust operation parameters of said |
| 13 | processors in said MP system. |
| 1 | 25. (original) The MP system of claim 24, wherein said controller is one of said |
| 2 | plurality of processors in said MP system. |
| 1 | 26. (original) The MP system of claim 24, further comprising: |
| 2 | circuitry for applying said controls to adjust operation parameters of cooling |
| 3 | systems for said MP system. |
| 1 | 27. (original) The MP system of claim 24, wherein said MP system comprises a single |
| 2 | multiprocessor very large scale integrated circuit (VLSI) chip. |
| 1 | 28. (original) The MP system of claim 27, wherein said MP system comprises a cooling |
| 2 | means for said multiprocessor VLSI chip. |
| 1 | 29. (original) The MP system of claim 28, wherein said cooling means comprises a |
| 2 | single chip cooling fan. |
| 1 | 30. (original) The MP system of claim 27, wherein said MP system comprises a self- |
| 2 | contained MP system, said self-contained MP system comprising a plurality of said |
| 3 | multiprocessor VLSI chips, said self-contained MP system further comprising a first |
| 4 | controllable cooling system. |

- 1 31. (original) The MP system of claim 30, wherein said MP system comprises a rack MP
- 2 system, said rack MP system comprising a plurality of said self-contained MP systems
- 3 and a controllable rack cooling system.
- 1 32. (original) The MP system of claim 31, wherein said MP system comprises a plurality
- of said rack MP systems, said MP system further comprising a controllable MP system
- 3 cooling means.
- 1 33. (original) The MP system of claim 24, wherein said first parameters comprise policy
- 2 of operation parameters for said MP system.